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Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (_), the underscore (_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.onsemi.com. Please email any questions regarding the system integration to Fairchild_questions@onsemi.com.

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MM74HCT245
Octal 3-STATE Transceiver

General Description

The MM74HCT245 3-STATE bi-directional buffer utilizes advanced silicon-gate CMOS technology and is intended for two-way asynchronous communication between data buses. It has high drive current outputs which enable high speed operation even when driving large bus capacitances. This circuit possesses the low power consumption of CMOS circuitry, yet has speeds comparable to low power Schottky TTL circuits.

This device is TTL input compatible and can drive up to 15 LS-TTL loads, and all inputs are protected from damage due to static discharge by diodes to V_{CC} and ground.

The MM74HCT245 has one active low enable input ($\overline{G}$), and a direction control (DIR). When the DIR input is HIGH, data flows from the A inputs to the B outputs. When DIR is LOW, data flows from B to A.

MM74HCT devices are intended to interface between TTL and NMOS components and standard CMOS devices. These parts are also plug-in replacements for LS-TTL devices and can be used to reduce power consumption in existing designs.

Features

- TTL input compatible
- 3-STATE outputs for connection to system busses
- High output drive current: 6 mA (min)
- High speed: 16 ns typical propagation delay
- Low power: 80 μA (74HCT Series)

Ordering Code:

Order Number	Package Number	Package Description
MM74HCT245WM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
MM74HCT245SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
MM74HCT245MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
MM74HCT245N	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Connection Diagram

Pin Assignments for DIP, SOIC, SOP and TSSOP

Top View
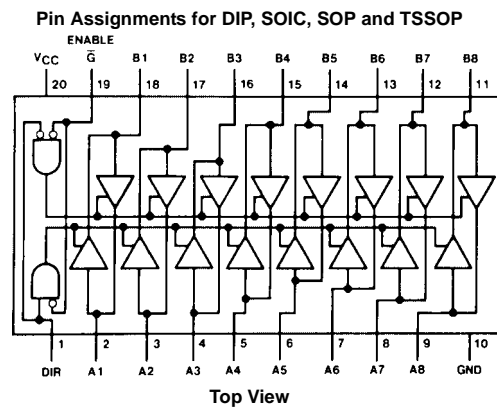
Truth Table

Control		Operation
Inputs		
$\overline{G}$	DIR	245
L	L	B data to A bus
L	H	A data to B bus
H	X	isolation

H = HIGH Level
L = LOW Level
X = Irrelevant

MM74HCT245

Logic Diagram
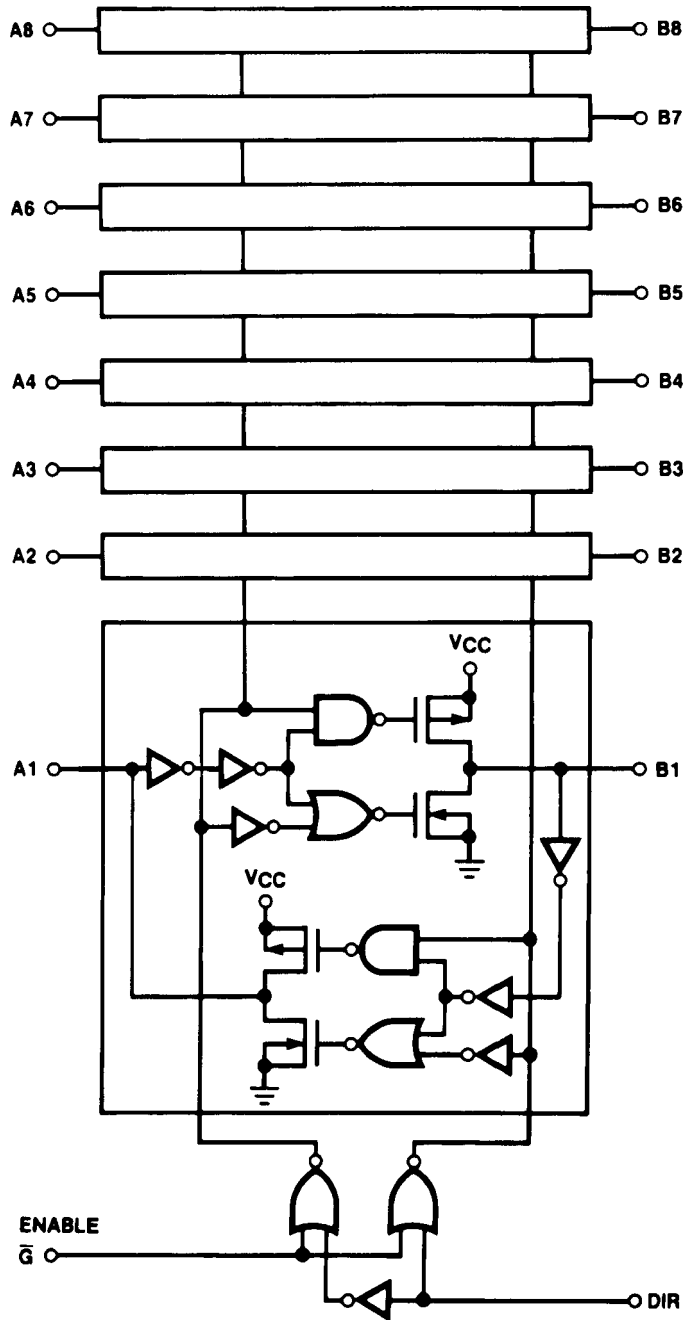
Absolute Maximum Ratings(Note 1)

(Note 2)

Supply Voltage (V_{CC})	−0.5 to +7.0V
DC Input Voltage (V_{IN})	−1.5 to V_{CC} +1.5V
DC Output Voltage (V_{OUT})	−0.5 to V_{CC} +0.5V
Clamp Diode Current (I_{IK}, I_{OK})	±20 mA
DC Output Current,	±35 mA
DC V_{CC} or GND Current, per pin (I_{CC})	±70 mA
Storage Temperature Range (T_{STG})	−65°C to +150°C
Power Dissipation (P_D)	
(Note 3)	600 mW
S.O. Package only	500 mW
Lead Temperature (T_L)	
(Soldering 10 seconds)	260°C

Recommended Operating Conditions

	Min	Max	Units
Supply Voltage (V_{CC})	4.5	5.5	V
DC Input or Output Voltage			
(V_{IN}, V_{OUT})	0	V_{CC}	V
Operating Temperature Range (T_A)	−40	+85	°C
Input Rise or Fall Times			
(t_r, t_f)		500	ns

Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 3: Power Dissipation temperature derating — plastic "N" package: −12 mW/°C from 65°C to 85°C.

DC Electrical Characteristics

(V_{CC} = 5V ± 10%, unless otherwise specified.)

Symbol	Parameter	Conditions	T_A = 25°C Typ	T_A = 25°C Guaranteed Limits	T_A = −40 to 85°C	T_A = −55 to 125°C	Units
V_{IH}	Minimum HIGH Level Input Voltage			2.0	2.0	2.0	V
V_{IL}	Maximum LOW Level Input Voltage			0.8	0.8	0.8	V
V_{OH}	Minimum HIGH Level Output Voltage	V_{IN} = V_{IH} or V_{IL} $|I_{OUT}|$ = 20 μA	V_{CC}	V_{CC}− 0.1	V_{CC}− 0.1	V_{CC}− 0.1	V
		$|I_{OUT}|$ = 6.0 mA, V_{CC} = 4.5V	4.2	3.98	3.84	3.7	V
		$|I_{OUT}|$ = 7.2 mA, V_{CC} = 5.5V	5.2	4.98	4.84	4.7	V
V_{OL}	Maximum LOW Level Voltage	V_{IN} = V_{IH} or V_{IL} $|I_{OUT}|$ = 20 μA	0	0.1	0.1	0.1	V
		$|I_{OUT}|$ = 6.0 mA, V_{CC} = 4.5V	0.2	0.26	0.33	0.4	V
		$|I_{OUT}|$ = 7.2 mA, V_{CC} = 5.5V	0.2	0.26	0.33	0.4	V
I_{IN}	Maximum Input Current	V_{IN} = V_{CC} or GND, V_{IH} or V_{IL}, Pin 1 or 19		±0.1	±1.0	±1.0	μA
I_{OZ}	Maximum 3-STATE Output Leakage Current	V_{OUT} = V_{CC} or GND $\overline{G}$ = V_{IH}		±0.5	±5.0	±10	μA
I_{CC}	Maximum Quiescent Supply Current	V_{IN} = V_{CC} or GND I_{OUT} = 0 μA		8	80	160	μA
		V_{IN} = 2.4V or 0.5V (Note 4)	0.6	1.0	1.3	1.5	mA

Note 4: Measured per input. All other inputs at V_{CC} or ground.

AC Electrical Characteristics

V_{CC} = 5.0V, t_r = t_f = 6 ns, T_A = 25°C (unless otherwise specified)

Symbol	Parameter	Conditions	Typ	Guaranteed Limit	Units
t_{PHL}, t_{PLH}	Maximum Output Propagation Delay	C_L = 45 pF	16	20	ns
t_{PZL}, t_{PZH}	Maximum Output Enable Time	C_L = 45 pF R_L = 1 kΩ	29	40	ns
t_{PLZ}, t_{PHZ}	Maximum Output Disable Time	C_L = 5 pF R_L = 1 kΩ	20	25	ns

AC Electrical Characteristics

V_{CC} = 5.0V ± 10%, t_r = t_f = 6 ns (unless otherwise specified)

Symbol	Parameter	Conditions	T_A = 25°C Typ	T_A = 25°C Guaranteed Limits	T_A = −40 to 85°C	T_A= −55 to 125°C	Units
t_{PHL}, t_{PLH}	Maximum Output Propagation Delay	C_L = 50 pF	17	23	29	34	ns
		C_L = 150 pF	24	30	38	45	ns
t_{PZL}	Maximum Output Enable Time	R_L = 1 kΩ C_L = 50 pF	31	42	53	63	ns
t_{PZH}	Maximum Output Enable Time	R_L = 1 kΩ C_L = 50 pF	23	33	41	49	ns
t_{PHZ}, t_{PLZ}	Maximum Output Disable Time	R_L = 1 kΩ C_L = 50 pF	21	30	38	45	ns
t_{THL}, t_{TLH}	Maximum Output Rise and Fall Time	C_L = 50 pF	8	12	15	18	ns
C_{IN}	Maximum Input Capacitance		10	15	15	15	pF
C_{OUT}	Maximum Output/Input Capacitance		20	25	25	25	pF
C_{PD}	Power Dissipation Capacitance	$\overline{G}$ = V_{CC} (Note 5)	7				pF
		$\overline{G}$ = GND	100				pF

Note 5: C_{PD} determines the no load power consumption, P_D = C_{PD} V_{CC}2 f + $I_{CC}V_{CC}$, and the no load dynamic current consumption, I_S = C_{PD} V_{CC} f + I_{CC}.

Physical Dimensions inches (millimeters) unless otherwise noted
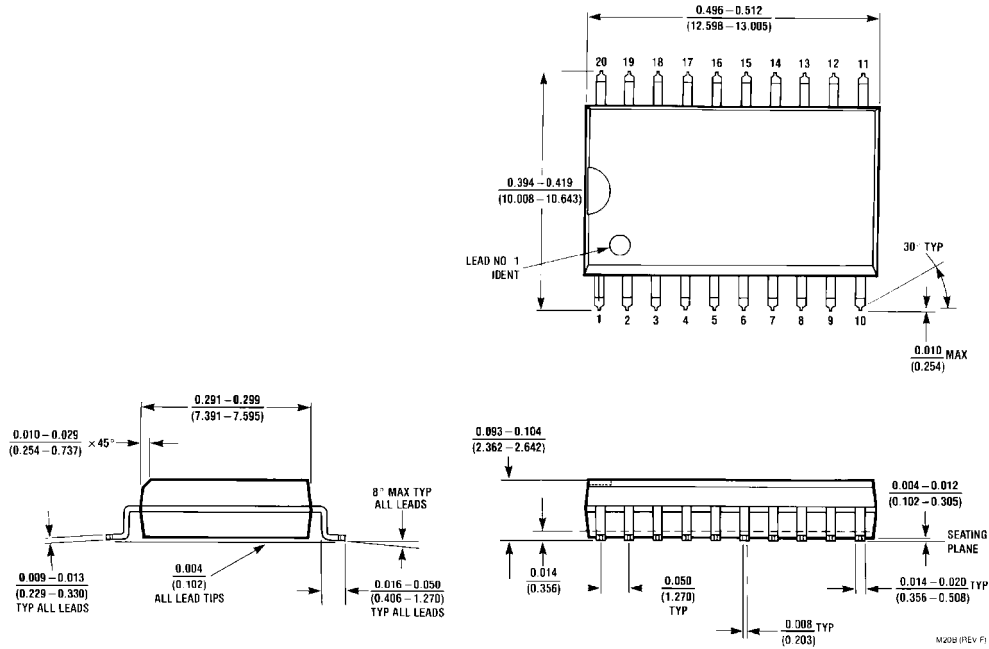
20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
Package Number M20B

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

12.6±0.10
-A-

0.40 TYP

20

11

7.8

3.9

5.3±0.10
-B-

PIN #1 IDENT.

1

10

△ 0.2 C B A
ALL LEAD TIPS

20 19

12 11

5.01 TYP

9.27 TYP

(2.13 TYP)

1   2

9   10

1.27 TYP

0.6 TYP

LAND PATTERN RECOMMENDATION

ALL LEAD TIPS
△ 0.1 C

2.1 MAX.

-C-

1.27 TYP

1.8±0.1

0.15±0.05

0.35-0.51
⊕ 0.12 Ⓜ C A

DIMENSIONS ARE IN MILLIMETERS

NOTES:
A. CONFORMS TO EIAJ EDR-7320 REGISTRATION,
   ESTABLISHED IN DECEMBER, 1998.
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD
   FLASH, AND TIE BAR EXTRUSIONS.

M20DRevB1

SEE DETAIL A

0.15-0.25

DETAIL A

7° TYP

GAGE PLANE

0.25

0°-8° TYP

0.60±0.15

1.25

SEATING PLANE

20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M20D

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

6.5±0.1
-A-
-0.20
20
11
-C-
6.4
4.4±0.1 -B-
3.2
1
10
PIN #1 IDENT.
0.2 C B A
ALL LEAD TIPS

4.16 7.72
1.78
0.42
0.65
LAND PATTERN RECOMMENDATION

0.1 C
ALL LEAD TIPS
0.90 +0.15 -0.10
1.2 max
-C-
0.1±0.05
0.65
0.19-0.30
0.10 M A B S C S

DIMENSIONS ARE IN MILLIMETERS
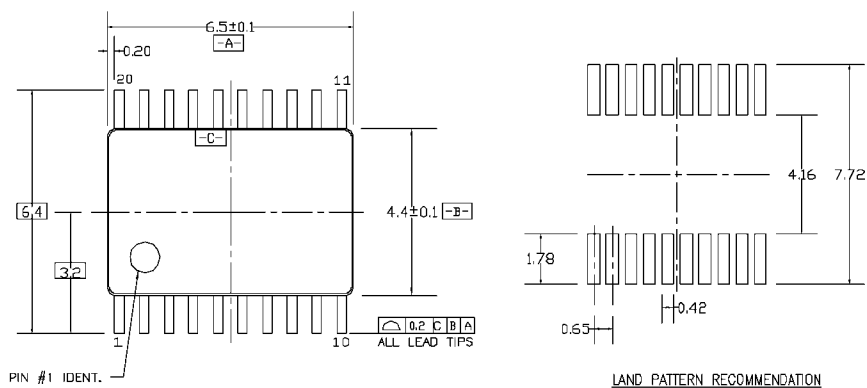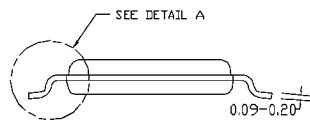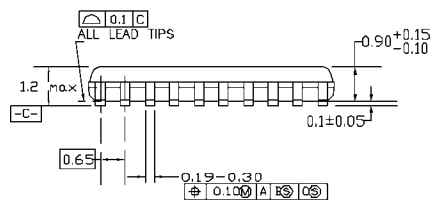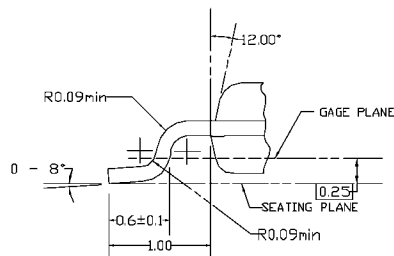
SEE DETAIL A
0.09-0.20
12.00°
R0.09min
GAGE PLANE
0 - 8°
0.25
SEATING PLANE
0.6±0.1
R0.09min
1.00
DETAIL A

NOTES:

A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AC, REF NOTE 6, DATE 7/93.

B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.

D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC20REVD1

20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
Package Number MTC20

www.fairchildsemi.com

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide
Package Number N20A

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PUBLICATION ORDERING INFORMATION

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